

67,200-261; TSMC 99-529/30
Serial Number 09/821,521

REMARKS

Favorable reconsideration of this application in light of the above amendments and the following remarks is respectfully requested.

Claims 9 and 11-17 are pending in this application. No claims are amended herein. No claims are canceled herein. No claims have been allowed.

Claim Rejections - 35 U.S.C. § 103

The Examiner has rejected claims 9, 11-14 and 16 under 35 U.S.C. § 103(a) as being unpatentable over Jacobson et al. (U.S. Patent No. 6,294,401; hereinafter "Jacobson") in view of Shiga (U.S. Patent No. 5,396,101).

First, applicant notes that the Examiner within the paragraph bridging pages 2-3 of the office action made FINAL acknowledges that Jacobson does not disclose a spirally patterned conductor layer having formed within its center a microelectronic structure comprising a series of at least four electrically interconnected sub-patterns to attenuate eddy currents within the microelectronic structure (in accord with applicant's claim 9 and claim 16).

Applicant also notes that the Examiner at page 3, first partial paragraph, last sentence of the office action made FINAL predicates suggestion or motivation to modify or combine Jacobson with Shiga (to provide applicant's invention as disclosed and claimed within claim 1 and claim 16) upon Shiga's disclosure of attenuation of eddy currents within a microelectronic device such as to provide an increase in operating frequency of the microelectronic device.

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In response, applicant notes that the Examiner has accurately cited Shiga's disclosure with respect to attenuation of eddy currents and increase in operating frequency within a microelectronic device. However, with respect to Jacobson, applicant notes that Jacobson's electronic identification tag (Fig. 4 and col. 7, lines 9-30) which comprises an inductor and a pair of interconnected capacitors is unlikely to experience eddy currents in its static state since there is no indication that Jacobson's electronic identification tag is powered in its static state. In addition applicant notes that Jacobson's electronic identification tag's response is a digital response provided at a resonant frequency and activated by a magnetic field from an external coil controlled by a separate logic circuit within Jacobson's electronic identification tag. Applicant is unable to locate within Jacobson any suggestion that eddy currents would actually occur incident to external magnetic field activation of Jacobson's electronic identification tag. Applicant is also unable to ascertain that additional patterning of Jacobson's pair of interconnected capacitors to effect eddy current attenuation would facilitate a desired result within Jacobson's electronic identification tag, such as an increased operating frequency, since Jacobson's electronic identification tag operates at a resonant frequency which presumably need not necessarily be (and presumably is not) an increased operating frequency..

Thus, applicant asserts that Jacobson may not properly be combined with Shiga to reject any of applicant's claims to applicant's invention under 35 U.S.C. § 103(a) for reasons as suggested by the Examiner, since the reasons as suggested by the Examiner appear inapplicable to Jacobson's invention. The fact that references can be combined or modified is by itself insufficient suggestion or motivation for modification or combination of the references for providing a prima facie case of obviousness under 35 U.S.C. § 103. MPEP 2143.01.

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In light of the foregoing response, applicant respectfully requests that the Examiner's rejections of claims 9, 11-14 and 16 under 35 U.S.C. § 103(a) as being unpatentable over Jacobson in view of Shiga be withdrawn.

The Examiner has rejected claims 15-16 is rejected under 35 U.S.C. § 103(a) as being unpatentable over Jacobson in view of DiCaprio et al. (U.S. Patent No. 6,452,278; hereinafter "DiCaprio").

Applicant assumes that the Examiner might have intended rejection of claims 15 and 17 rather than 15-16.

Applicant notes that the Examiner at page 4, lines 13-15 of the office action made FINAL predicates suggestion or motivation for modification or combination of Jacobson with DiCaprio (to provide applicant's claimed invention having a bond pad and a looped bond wire connected to the bond pad) upon DiCaprio's disclosure (col. 2, lines 48-50) of a desire to minimize a height of an electronics package.

In response, applicant asserts that there exists no suggestion or motivation for modification or combination of Jacobson with DiCaprio for reasons as cited by the Examiner insofar as Jacobson's electronic identification tag is activated by a magnetic field from an external coil and thus requires no apparent bond wire connection in a first instance, whether or not the bond wire connection minimizes the height of Jacobson's package. In addition, applicant notes that applicant's multiply looped bond wire (as claimed within claim 17 and as is apparently not disclosed within either Jacobson or DiCaprio) would likely contribute to an increase in height

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of an electronics package rather than a decrease in height of the electronics package and thus DiCaprio teaches away from that which is disclosed and claimed by applicant. MPEP 2141.02.

Thus, since the reasons as advanced by the Examiner for combining Jacobson with DiCaprio appear inapplicable to Jacobson or applicant's invention, and since DiCaprio appears to teach away from that which is disclosed and claimed by applicant, applicant asserts that Jacobson may not properly be combined with DiCaprio for purposes of rejecting any of applicant's claims to applicant's invention under 35 U.S.C. § 103.

In light of the foregoing response, applicant respectfully requests that the Examiner's rejection of claims 15-16 under 35 U.S.C. § 103(a) as being unpatentable over Jacobson in view of DiCaprio be withdrawn.

Other Considerations

The Examiner has newly cited no additional prior art of record not employed in rejecting applicant's claims to applicant's invention.

No fee is due as a result of this response.

SUMMARY

Applicant's invention as disclosed and claimed within amended claim 9, amended claim 15, claim 16 and claim 17 is directed towards a microelectronic fabrication, wherein the microelectronic fabrication comprises formed over a substrate a spirally patterned conductor layer. Within applicant's invention, the spirally patterned conductor layer terminates in a microelectronic structure formed within the center of the spirally patterned conductor layer.

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Within applicant's invention, the spirally patterned conductor layer forms a planar spiral inductor, and the microelectronic structure formed within the center of the spirally patterned conductor layer comprises a series of electrically interconnected sub-patterns (preferably at least four) to which may be bonded a bond wire having incorporated therein a minimum of one loop (and preferably a plurality of loops), such as to attenuate eddy currents within the microelectronic structure. The prior art of record employed in rejecting applicant's claims to applicant's invention may not properly be modified or combined for purposes of rejecting applicant's claims to applicant's invention, for reasons as suggested by the Examiner.

CONCLUSION

On the basis of the above amendments and remarks, reconsideration of this application, and its early allowance, are respectfully requested.

Any inquiries relating to this or earlier communications pertaining to this application may be directed to the undersigned attorney at 248-540-4040.

Respectfully submitted,



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